CPI1008KR82R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

3.0

0.5

0.0



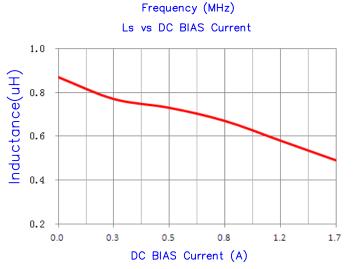
- B 2.00 [.079] ± 0.20[.008]
- C 0.90 [.035] ± 0.10[.004]
- D 0.60 [.024] ± 0.20[.008]



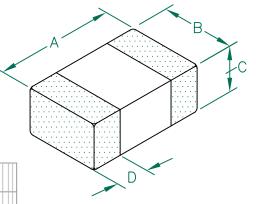
100

1.000

Ls vs Frequency

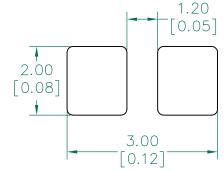


10





LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering. add 0.763 [0.030] to this dimension)

ELECTRICAL CHARACTERISTICS:			
	L (μΗ) @ 1MHz ± 20%	DCR ($\frac{\Omega}{2}$) ± 25%	l (Max)
Nom	0.820	0.100	
Min	0.656	0.075	
Max	0.984	0.125	1700mA

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS

